

# **APPROVAL SHEET**

# **MULTILAYER CERAMIC CAPACITOR**

Automotive Grade (AEC-Q200 Qualified)

Approved by customer : (signing or stamping here)						

SAMWHA CAPACITOR CO., LTD.						
Prepared by	Prepared by Checked by Approved by					
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2020. 05. 25.

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< SPECIFICATION SUMMARY >							
SAMWHA Part no.		CQ1	L608C0G101J101NRB				
Туре	,	*MLCC fo	or Automotive Application				
Items	Specification	Unit	Test Conditions				
Capacitance	100	pF	Testing Frequency: 1 ±0.1 MHz				
Capacitance Tolerance	± 5	%	Testing Voltage : 1 ±0.2 Vrms				
Dissipation Factor	Max. 0.1	%	Should be measured at 25℃.				
Insulation Resistance	Min. 100,000	MΩ	Should be measured with a DC voltage not exceeding rated voltage at 25℃ for 2 minutes of charging.				
	1.60 ±0.15	L (mm)	Capacitance Tolerance Code page 1/9				
Chip Size	0.80 ±0.10	W (mm)	Chip size page 2/9				
	0.80 ±0.10	<b>T</b> (mm)	Characteristics & Test Method page 3/9~6/9				
*Thin Layer Large-Capacitance Type							

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**STANDARD** NO SW - Q - 01A Enactment: **MULTILAYER CERAMIC CAPACITOR** Feb. 1, 2010 1 / 9 Page **Automotive Grade** 

\*Caution: ECU/ Power Train/ Safety module/ Etc.

Please contact sales representatives or product engineers before using

these Automotive products.

## 1. General Code

(1) Type Designation

CQ	<u>1608</u>	C0G	<u>101</u>	<u>J</u>	<u>101</u>	N	<u>R</u>	В
(1)	(2)	(3)	(4)	(5)	(6)	(7)	(8)	(9)

- 1) Multilayer Ceramic Capacitor (Automotive Grade)
- 2) Size Code:

This is expressed in tens of a millimeter.

The first two digits are the length, The last two digits are width.

#### 3) Temperature Coefficient Code

Classification	Code	Temperature Range	Capacitance Tolerance
Class I	C0G	-55 to +125℃	±30 ppm/℃
	X7R	-55 to +125℃	±15%
	X7S	-55 to +125℃	±22%
Class II	X7T	-55 to +125℃	+22% ~ -33%
	X6S	-55 to +105℃	±22%
	X5R	-55 to +85℃	±15%

# 4) Capacitance Code(Pico farads):

The nominal Capacitance Value in pF is expressed by three digit numbers.

The first two digits represents significant figures and the last digit denotes the number of zero ex) 104 = 100000 pF

R denotes decimal

8R2 = 8.2 pF

# 5) Capacitance Tolerance Code

Code	Tolerance	
В	± 0.1 pF	
С	± 0.25 pF	
D	± 0.5 pF	
F	± 1.0 %	

Code	Tolerance		
G	± 2.0 %		
J	± 5 %		
K	± 10 %		
M	± 20 %		

#### 6) Voltage Code

Code	6R3	100	160	250	350	500	101	201	251	501	631	102	202	302
Rated	DC	DC	DC	DC	DC	DC	DC	DC	DC	DC	DC	DC	DC	DC
Voltage	6.3V	10V	16V	25V	35V	50V	100V	200V	250V	500V	630V	1KV	2KV	3KV

#### 7) Termination Code

N: Nickel-Tin Plate

A: Nickel-Tin Plate -> Soft Termination Type

## 8) Packing Code

R: 7" Reel Type, L: 13" Reel Type, B: Bulk Type

# 9) Thickness option

Thickne	Thickness (mm)		Thickne	Code	
t	Tolerance(±)	Code	t	Tolerance(±)	Code
0.50	0.05	Blank	1.35	0.20	Н
0.60	0.10	Α	1.60	0.20	Į
0.80	0.10	В	1.80	0.20	J
0.85	0.15	В	2.00	0.25	K
1.00	0.15	E	2.50	0.25	L
1.10	0.15	E	2.80	0.30	M
1.15	0.15	E	3.20	0.30	N
1.25	0.15	Е	5.00	0.40	0
1.30	0.20	E			

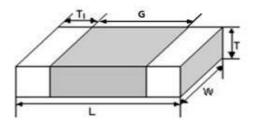
<sup>\*3216</sup> Size  $\geq 2.2\mu F$  100V  $\Rightarrow$  T : Tol $\pm 0.30$ 

# 2. Temperature Characteristics

See Page 6/9 (No.21)

# 3. Constructions and Dimensions

# (1) Dimensions



		Dimension							
Size Code	EIA Code	Length		Wie	dth		O(i)		
		L	Tol(±)	W	Tol(±)	T1(min.)	G(min.)		
1005	0402	1.00	0.05	0.50	0.05	0.05	0.30		
1608	0603	1.60	0.15	0.80	0.10	0.10	0.50		
2012	0805	2.00	0.20	1.25	0.15	0.10	0.65		
3216	1206	3.20	0.30	1.60	0.20	0.15	1.00		
3225	1210	3.20	0.40	2.50	0.25	0.15	1.05		
4520	1808	4.50	0.40	2.00	0.25	0.20	1.50		
4532	1812	4.50	0.40	3.20	0.30	0.20	1.50		
5750	2220	5.70	0.50	5.00	0.40	0.30	1.85		

<sup>\*3216</sup> Size  $\geq 2.2\mu F$  100V  $\Rightarrow$  L, W : Tol $\pm 0.30$ (Unit: mm)

# (2) Construction of Termination



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# Specifications and Test Methods (For Automotive Applications)

No.	AEC-Q200				Test Methods and Conditions				
NO.	Test	Item	Class I	Class II	rest methods and Conditions				
1	Pre-and Post-Stress Electrical Test			-					
		Appearance	No defects which may affect	performance					
		Capacitance Change	Within ±2.5% or ±0.25pF (Whichever is larger)	Within ±10.0% (*Within ±12.5%)					
2	High Temperature Exposure (Storage)	Q/D.F.	30pF min.: Q≥350 10pF and over, 30pF and below:Q≥275+5C/2 10pF max : Q≥200+10C C: Nominal Capacitance (pF)	Rated Voltage 16V min.: 0.05 max. 10V: 0.075 max. *0.2 max.	Temperature: Max. operating temperature±3 °C  Maintenance Time: 1000+48/-0 hrs  Let sit for 24±2 hours at room temperature, then measure.				
		I.R.	More than $10,000M\Omega$ or $500\Omega$ (Whichever is smaller)	P·F (*25Ω·F)					
		Appearance	No defects which may affect	performance	Perform the 1000 cycles according to the four heat treatments				
		Capacitance Change	Within ±2.5% or ±0.25pF (Whichever is larger)	Within ±10.0% (*Within ±12.5%)	listed in the following table.  Let sit for 24±2 hours at room temperature, then measure.				
			30pF min.:Q≧1000	Rated Voltage 16V min.: 0.05 max.	Step 1 2 3 4				
3	Temperature Cycle	Q/D.F.	30pF max.:Q≧400+20xC C: Nominal Capacitance (pF)	10V: 0.075 max. *0.2 max.	Temp.(°C)   Min. operating temp. +0/-3   Room temp.   Roo				
		I.R.	More than 10,000M $\Omega$ or 500 $\Omega$ -F (*50 $\Omega$ -F) (Whichever is smaller)		Time(min)         15±3         1         15±3         1           Initial measurement         15±3         1         15±3         1				
4	Destructive Physical Analysis		No defects or abnormalities		Perform the initial measurement according to Note 1 for Class II.  Per EIA-469				
		Appearance	No defects which may affect	performance	Temperature: 25~65°C, Humidity: 80~98%				
		Capacitance Change	Within ±3.0% or±0.30pF (Whichever is larger)	Within ±12.5%	Cycle Time : 24 hrs/cycle, 10 cycles Let sit for 24±2 hours at room temperature, then measure.				
5	Moisture Resistance	Q/D.F.	30pF min.: Q≥350 10pF min. and 30pF max.: Q≥275+5/2xC 10pF max.: Q≥200+10xC C: Nominal Capacitance (pF)	Rated Voltage 16V min.: 0.05 max. 10V: 0.075 max. *0.2 max.	80-98% 80				
		I.R.	More than 10,000M $\Omega$ or 500 $\Omega$ (Whichever is smaller)	ŀF (*50Ω·F)	1 2 3 4 5 6 7 8 9 10 11 12 13 14 15 16 17 18 19 20 21 22 23 24  Time (hrs)				
		Appearance	No defects which may affect	performance					
		Capacitance Change	Within ±3.0% or ±0.30pF (Whichever is larger)	Within ±12.5%	Temperature : 85±3 °C Humidity : 80~85%				
6	Biased Humidity	Q/D.F.	30pF min.: Q≥200 30pF max.: Q≥100+10/3×C C: Nominal Capacitance (pF)	Rated Voltage 16V min.: 0.05 max. 10V: 0.075 max. *0.2 max.	Maintenance Time: 1000+48/-0 hrs Let sit for 24±2 hours at room temperature, then measure.				
		I.R.	More than 1,000M $\Omega$ or 50 $\Omega$ ·F (Whichever is smaller)	(*5Ω·F)	The charge/discharge current is less than 50mA.				
		Appearance	No defects which may affect	performance	Temperature : Max operating Temp.±3℃				
		Capacitance Change	Within ±3.0% or ±0.30pF (Whichever is larger)	Within ±12.5%	Applied Voltage: Rated Voltage x 200% (*100%)  Maintenance Time: 1000+48/-0 hrs				
7	Operational Life	Q/D.F.	30pF min.:Q≥350 10pF min. and 30pF max.: Q≥275+5/2xC 10pF max.: Q≥200+10xC C: Nominal Capacitance (pF)	Rated Voltage 16V min.: 0.05 max. 10V: 0.075 max. *0.2 max.	Let sit for 24±2 hours at room temperature, then measure.  The charge/discharge current is less than 50mA.  Initial Measurement for Class II  Applied 200% of the rated voltage for one hour at Max operating  Temp.±3°C				
		I.R.	More than 1,000M $\Omega$ or 50 $\Omega$ -F (*5 $\Omega$ -F) (Whichever is smaller)		Remove and let sit for 24±2 hours at room temperature, then measure.				

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# Specifications and Test Methods (For Automotive Application)

1	AEC-Q200		Specif	ication		Toot Mothods and Conditions			
No.		Item	Class I	Class	II	Test Methods and Conditions			
8	External Visu	al	No defects or abnormalities			Visual inspection			
9	9 Physical Dimension		Within the specified dimensions			Using calipers			
		Appearance	No defects which may affect p	erformance					
		Capacitance Change	Within the specified tolerance						
10	Resistance to Solvents	Q/D.F.	30pF min.: Q≥1000 30pF max.: Q≥400+20xC C: Nominal Capacitance (pF)	16V:	0.025 max. 0.03 max. 0.035 max. 0.05 max.	Per MIL-STD-202 Method 215			
		I.R.	More than 10,000M $\Omega$ or 500 $\Omega$ -F (Whichever is smaller)	(*50Ω·F)					
		Appearance	No defects which may affect p	erformance					
		Capacitance Change	Within the specified tolerance			Three shocks in each direction should be applied along 3 mutually perpendicular axes of the test specimen (18 shocks)			
11	Mechanical Shock	Q/D.F.	30pF min.:Q≥1000 30pF max.:Q≥400+20xC C: Nominal Capacitance (pF)	16V:	0.025 max. 0.03 max. 0.035 max. 0.05 max.	Test Pulse Wave form : Half-sine Duration : 0.5ms Peak value : 1,500G			
	I.R.		More than 10,000M $\Omega$ or 500 $\Omega$ -F (Whichever is smaller)			Velocity change : 4.7m/s			
		Appearance	No defects or abnormalities						
		Capacitance Change	Within the specified tolerance			The specimens should be subjected to a simple harmonic motion			
12	Vibration	Q/D.F.	30pF min.:Q≥1000 30pF max.:Q≥400+20xC C: Nominal Capacitance (pF)	16V:	0.025 max. 0.03 max. 0.035 max. 0.05 max.	having a total amplitude of 1.5mm. The entire frequency range of 10 to 2,000 Hz and return to 10 Hz should be traversed in 20 minutes. This cycle should be performed 12 times in each of three mutually perpendicular directions (total of 36 times).			
		I.R.	More than 10,000M $\Omega$ or 500 $\Omega$ -F (Whichever is smaller)						
		Appearance	No defects which may affect p	erformance					
		Capacitance Change	Within the specified tolerance			Temperature (Eutectic solder solution) : 260±5°C			
13	Resistance to Soldering Heat	Q/D.F.	30pF min.:Q≥1000 30pF max.:Q≥400+20xC C: Nominal Capacitance (pF)	16V: 10V:	0.025 max. 0.03 max. 0.035 max. 0.05 max.	Dipping Time: 10±1s Let sit for 24±2 hours at room temperature, then measure.  Initial measurement Perform the initial measurement according to Note 1 for Class II.			
		I.R.	More than 10,000M $\Omega$ or 500 $\Omega$ -F (Whichever is smaller)	,		_			
		Appearance	No defects which may affect p	erformance		Perform the 300 cycles according to the two heat treatments listed			
		Capacitance	Within ±2.5% or ±0.25pF			in the following table.			
		Change	(Whichever is larger)	Within ±15%		Transfer Time: 20sec. max.			
14	Thermal Shock	Q/D.F.	30pF min.:Q≥1000 30pF max.:Q≥400+20xC C: Nominal Capacitance (pF)	16V:	0.025 max. 0.03 max. 0.035 max. 0.05 max.	Cet sit for 24±2 hours at room temperature, then measure.			
		I.R.	More than 10,000M $\Omega$ or 500 $\Omega$ -F (Whichever is smaller)			Initial measurement Perform the initial measurement according to Note 1 for Class II.			

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# Specifications and Test Methods (For Automotive Application)

Τ	AEC-Q200 Test Item		· · · · · · · · · · · · · · · · · · ·	fication	Test Methods and Conditions				
No.			Class	Class II					
		Appearance Capacitance	No defects which may affect pe	erformance					
15	ESD	Change Q/D.F.	Rated Voltage 50V: 0.025 max.  30pF min.:Q≥1000 30pF max.:Q≥400+20xC 16V: 0.035 max. C: Nominal Capacitance (pF)  Rated Voltage 50V: 0.025 max.  16V: 0.035 max.  Per AEC-Q200-002						
		I.R.	More than 10,000M $\Omega$ or 500 $\Omega$ ·F (Whichever is smaller)	*0.125 max.  *50Ω·F)					
16	Solderability		95% of the terminations is to be s	oldered evenly and continuously.	<ul> <li>(a) Preheat at 155°C for 4 hours, and then immerse the capacitin a solution of ethanol and rosin. Immerse in eutectic solder solution for 5+0/-0.5 seconds at 235±5°C.</li> <li>(b) Steam aging for 8 hours, and then immerse the capacitor in solution of ethanol and rosin. Immerse in eutectic solder solution for 5+0/-0.5 seconds at 235±5°C.</li> <li>(c) Steam aging for 8 hours, and then immerse the capacitor in solution of ethanol and rosin. Immerse in eutectic solder solution for 120±5 seconds at 260±5°C.</li> </ul>				
		Appearance	No defects or abnormalities		The capacitance/Q/D.F. should be measured at 25 ℃ at the				
		Capacitance	Within the specified tolerance		frequency and voltage shown in the table.  Class Capacitance (C) Frequency Voltage				
		Change	within the specified tolerance		Class I C<1000pF 1±0.1kHz 0.5~5Vrms  C≥1000pF 1±0.1kHz 1±0.2Vrms				
17	Electrical Characteriza- tion		30pF min.:Q≥1000 30pF max.:Q≥400+20xC C: Nominal Capacitance (pF)	Rated Voltage 50V: 0.025 max. 25V: 0.03 max. 16V: 0.035 max. 10V: 0.05 max. *0.125 max.	$Class \ II \qquad C \le 10 \mu F \qquad 1 \pm 0.1 kHz \qquad 1 \pm 0.2 Vrms \\ \hline C > 10 \mu F \qquad 120 \pm 24 Hz \qquad 0.5 \pm 0.1 Vrms \\ \cdot \ Initial \ measurement \\ Perform \ the \ initial \ measurement \\ according \ to \ Note1 \ for \ Class \ II \\ \cdot \ Measurement \ after \ test \\ Take \ it \ out \ and \ set \ it \ for \ 24 \pm 2 \ hours \ (Class \ II)$				
		I.R. at 25℃	More than 100,000M $\Omega$ or 1,000 $\Omega$ -F (Whichever is smaller)	More than 10,000M $\Omega$ 500 $\Omega$ ·F (*50 $\Omega$ ·F) (Whichever is smaller)	then measure  Should be measured with a DC voltage not exceeding rated				
		I.R. at Max operating Temp.	More than 10,000M $\Omega$ or 100 $\Omega$ ·F (Whichever is smaller)	More than 1,000M $\Omega$ or 10 $\Omega$ F (*1 $\Omega$ F) (Whichever is smaller)	voltage at 25°C and Max. operating temperature for 2 minutes of charging.				
		Dielectric Strength	No dielectric breakdown or mecha	anical breakdown	Applied 250% of the rated voltage for 1~5 seconds The charge/discharge current is less than 50mA.				
		Appearance	No defects which may affect pe	erformance	Apply a force in the direction shown in the following figure for 60±5 seconds.  Support Solder Chip Printed circuit board before testing				
18	Board Flex	Capacitance Change	Within ±5.0% or ±0.5pF (Whichever is larger)	Within the specified tolerance	Radius 340  Printed circuit board under test  Flexure for Class I: 3mm max.  for Class II: 2mm max.				
	Torminal	Appearance	No defects which may affect pe	erformance	Apply 18N <sup>1)</sup> force in parallel with the test jig for 60±1 seconds.				
19	Terminal Strength	Capacitance Change	Within ±5.0% or ±0.5pF (Whichever is larger)	Within the specified tolerance	<sup>1)</sup> 10N for 1608(EIA:0603) size 2N for 1005(EIA:0402) size				

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# Specifications and Test Methods (For Automotive Application)

Na	AEC-Q200			Total Made a la con LO con l'écono								
No.	Test	Item	Class		Class II		Test Methods and Conditions					
			The chip endure follow	1,	Apply a force as shown in the following figure.							
			Chip Length	Thickne	ess (T)	Force	1 ' '	(i) Chip Length: 2.5mm max. (ii) Chip Length: 3.2m Beam Speed: 0.5mm/s Beam Speed: 2.5n				
			2.5mm may	T≤0.	≤0.5mm 8N		Beam Spe	ea : 0.511	im/s	Beam (	speed : 2.5	mm/s
20	Beam Load Te	est	2.5mm max.	T>0.	5mm	20N	ļ					
			3.2mm min.		5mm	15N		lŗ	on Board			
					1.25 54.5N		0.6					
			•			•					4 +	
		Capacitance Change			X7R : Wit X7S : Wit X6S : Wit	thin ±15% thin ±15% hin ±22% thin ±22% hin +22% ~ -33%	(i) Class I  The temperature coefficient is determined using the capacitance measured in step 3 as a reference. When cycling the temperature sequentially from step 1 through 5, the capacitance should be within the specified tolerance for the temperature coefficient.  The capacitance drift is calculated by dividing the differences between the maximum and minimum measured values in steps					
		Temperature Coefficient	0±30 ppm/℃				1, 3 and 5 by the capacitance value in step 3.				otopo	
							Step	1	2	3	4	5
21	Temperature Characteris- tics	'					Temp.(°C)	Room temp.±2	Min. operating temp.±3	Room temp.±2	Max. operating temp.±3	Room temp.±2
		Capacitance Drift	Within ±0.2% or ±0.05pF (Whichever is larger)				(ii) Class II The ranges of over the temp Max. operatin Initial measure	erature rag temper	ange from I ature.	Min. opera	ating tempe	rature to

In the case of "\*" is specifications for "Thin Layer Large Capacitance Type"

Note 1. Initial Measurement for Class II

Perform a heat treatment at 150+0/-10°C for one hour, and then let sit for 24±2 hours at room temperature, then measure.

(Unit: mm)

# **Packing**

- (1) Bulk Packing
  - 1 1000 pcs per polybag
  - ② 5 polybags per inner box
  - 3 10 inner boxes per out box
- (2) Reel Packing
  - ① 8~10 reels per inner box
  - 2 6 inner boxes per out box
- (3) Reel Dimensions



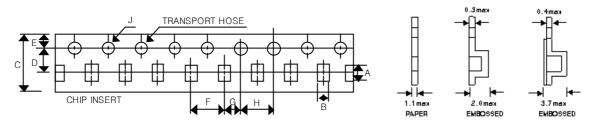


Mark	Size Code	EIA Code	Α	В	С	D	E	w
7 " Reel	1005~3225	0402~1210	Ф178±2	Ф <b>50Min</b>	Ф13±0.5	Ф21±0.8	2±0.5	10±1.5
	4520~4532	1808~1812	Ф180+0,-3	Ф60-0,+1	Ф13±0.2	Ф57-0+1	3±0.2	13±0.5
13 " Reel	1005~3225	0402~1210	Ф330±2	Φ <b>70Min</b>	Ф13±0.5	Ф21±0.8	2±0.5	10±1.5

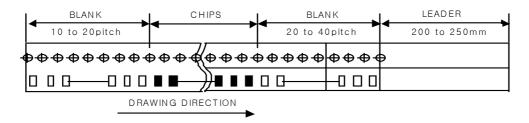
## (4) Number of Package

Size Code	EIA Code	7"	13"		
Size Code	EIA Code	Quantity(pcs)/Reel	Quantity(pcs)/Reel		
1005	0402	10,000	50,000		
1608	0603	4,000	15,000		
2012	0805	3,000 ~ 4,000	8,000 ~ 15,000		
3216	1206	2,000 ~ 4,000	6,000 ~ 10,000		
3225	1210	1,000 ~ 3,000	4,000 ~ 10,000		
4520	1808	1,500 ~ 3,000	-		
4532	1812	500 ~ 1,000	1,500 ~ 5,000		

# (5) Tape Dimensions



Size Code	EIA Code	А	В	С	D	E	F	G	Н	J
1005	0402	1.15±0.1	0.65±0.1	8.0±0.3	3.5±0.05	1.75±0.1	2.0±0.05	2.0±0.1	4.0±0.1	1.5±0.1
1608	0603	1.9±0.2	1.10±0.2	8.0±0.3	3.5±0.05	1.75±0.1	4.0±0.1	2.0±0.1	4.0±0.1	1.5±0.1
2012	0805	2.4±0.2	1.65±0.2	8.0±0.3	3.5±0.05	1.75±0.1	4.0±0.1	2.0±0.1	4.0±0.1	1.5±0.1
3216	1206	3.6±0.2	2.00±0.2	8.0±0.3	3.5±0.05	1.75±0.1	4.0±0.1	2.0±0.1	4.0±0.1	1.5±0.1
3225	1210	3.6±0.2	2.80±0.2	8.0±0.3	3.5±0.05	1.75±0.1	4.0±0.1	2.0±0.1	4.0±0.1	1.5±0.1
4520	1808	4.8±0.2	2.3±0.2	12.0±0.3	5.5±0.1	1.75±0.1	4.0±0.1 8.0±0.1	2.0±0.1	4.0±0.1	1.5±0.1
4532	1812	4.9±0.2	3.6±0.2	12.0±0.3	5.5±0.1	1.75±0.1	8.0±0.1	2.0±0.1	4.0±0.1	1.5±0.1



#### Caution

#### ► Storage Condition

When solderability is considered, capacitor are recommended to be used in 12 months.

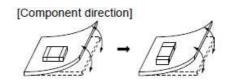
(1) Temperature:  $25^{\circ}$ C ±  $10^{\circ}$ C

(2) Relative Humidity: Below 70% RH

▶ The Regulation of Environmental Pollution Materials Never use materials mentioned below in MLCC products regulated this document. Pb, Cd, Hg, Cr<sup>+6</sup>, PBB(Polybrominated biphenyl), PBDE(Polybrominated diphenyl ethers), asbestos

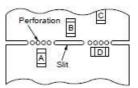
# ▶ Mounting Position

Choose a mounting position that minimizes the stress imposed on the chip during flexing or bending of the board.



Locate chip horizontal to the direction in which stress acts.

[Chip Mounting Close to Board Separation Point]



Chip arrangement Worst A-C- (B, D) Best

## ► Reflow Soldering

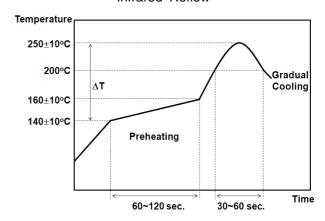
- 1. The sudden temperature change easily causes mechanical damages to ceramic components. Therefore, the preheating procedures should be required for the soldering of ceramic components.
- 2. Please refer to the recommended soldering profiles as shown in figures, and keep the temperature difference( $\triangle T$ ) within the range recommended in Table 1.

Table 1

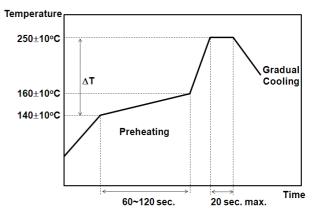
Size code (EIA Code)	Temperature Difference			
1005~3216 (0402~1206)	△T≤190℃			
3225 (1210)	△T≤130°C			

Recommended Reflow Soldering Profile for Lead Free Solder

Infrared Reflow



Vapor Reflow



#### Note

▶ 'Aging'/'De-aging' behavior of high dielectric constant type MLCCs (Typically represented by X7R temperature characteristic of which main composition is BaTiO<sub>3</sub>)

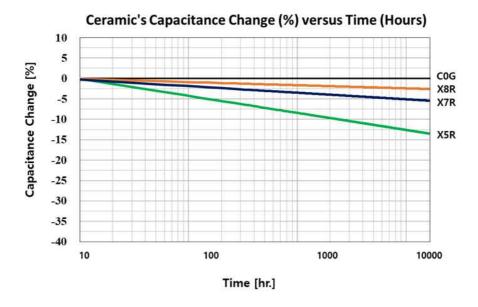
'Aging' / 'De-aging' Behavior of high dielectric MLCCs Please note that high dielectric type dielectric ceramic capacitors have a "normal" 'aging' behavior / characteristic, that is; their capacitance value decreases with time from its value when it was first manufactured. From that date, the capacitance value begins to decrease at a logarithmic rate defined by:

$$C_t = C_{24} (1 - k log 10 t)$$

where,

Ct : Capacitance value, t hours after the start of 'aging' C<sub>24</sub> : Capacitance value, 24 hours after its manufacture : Aging constant (capacitance decrease per decade-hour)

: time, in hours, from the start of 'aging'



The capacitance value can be restored (also known as 'de-aged') by exposing the component to elevated temperatures approaching its curie temperature (approximately 120°C). This 'de-aging' can occur during the component's solder-assembly onto the PCB, during life or temperature cycle testing, or by baking at 150°C for about 1 hour.